

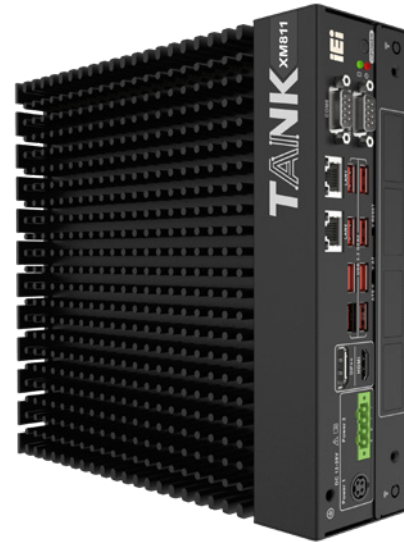
TANK-XM811

- High-Performance 12th Generation Intel® Core™ Processor
- Fanless Embedded Computer



Features

- Supported CPUs:
 - Intel® Core™ i5-12500TE 1.9 GHz (up to 4.3 GHz, 6-core, 35W TDP)
 - Intel® Core™ i7-12700TE 1.4 GHz (up to 4.6 GHz, 12-core, 35W TDP)
 - Intel® Core™ i9-12900TE 1.1 GHz (up to 4.8 GHz, 16-core, 35W TDP)
- 2 x 2.5G Ethernet ports
- Multiple USB ports and serial ports
- Multiple internal expansion boards for flexible selection
- Various optional backplanes and chassis
- CE/FCC compliant

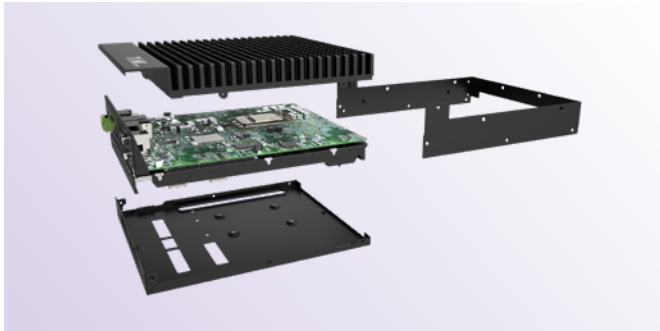


Specifications

Model Name		TANK-XM811
Chassis	Color	Black C
	Dimensions (WxDxH) (mm)	230.6 x 256.04 x 76.2
	System Fan	Fanless
	Chassis Construction	Extruded aluminum alloys
Motherboard	CPU	12 th Gen Intel® Core™ CPU 35/65W TDP Intel® Core™ i5-12500TE 1.9 GHz (up to 4.3 GHz, 6-core, 35W TDP) Intel® Core™ i7-12700TE 1.4 GHz (up to 4.6 GHz, 12-core, 35W TDP) Intel® Core™ i9-12900TE 1.1 GHz (up to 4.8 GHz, 16-core, 35W TDP)
	Chipset	R680E
	Memory	2 x SO-DIMM DDR4 3200 (8GB pre-installed) (up to 64GB)
Storage	HDD Bay	1 x 2.5" SATA 6Gb/s HDD/SSD bay
I/O Interfaces	Ethernet	2 x RJ-45, 1 x I225V & 1 x I225-LM 2.5GbE
	USB 3.2 Gen 2 (10Gb/s)	8
	COM	2 x RS-232/422/485, 4 x RS-232
	Digital I/O	12-bit (6-in/6-out) DB15
	Display Interface	1 x DP++, 1 x HDMI
Internal Expansions	M.2	1 x 2280 M-key (PCIe x4) 1 x 2230 A-key (USB+PCIe x1, supports vPRO)
	Expansion Backplane	Optional
Power	Power Input	12 ~ 28V DC
	Remote Power	1 x 2-pin
	Power Consumption	12V @ 8.8A (Intel® Core™ i9-12900TE with 16GB memory)
Reliability	Mounting	Wall mount
	Operating Temperature	-20°C ~ 60°C with air flow (CPU TDP35W & SSD) -20°C ~ 50°C with air flow (CPU TDP65W & SSD), 10% ~ 95% non-condensing
	Storage Temperature	-40°C ~ 85°C, 10% ~ 95%, non-condensing
	Operating Shock	Half-sine wave shock 5G, 11ms, 100 shocks per axis (SSD)
	Operating Vibration	MIL-STD-810G 514.6C-1 (with SSD)
	Weight (Net/Gross)	3.33/3.7 kg
	Safety / EMC	CE/FCC
	Watchdog Timer	Programmable 1 ~ 255 sec/min
OS	Supported OS	Windows® 10/11 IoT Enterprise/ Linux

Modular Design, Easy to Install

The mainboard is secured to the support bracket to prevent PCB from bending or warping. The three-layer structure consisting of heat spreader, mainboard and baseboard makes it easier to install CPU, memory and HDD, compared with the former TANK series.



Support High-performance Graphics Card

With IEI power board, it can support 3060 and other advanced graphics cards.

Maximum length of graphics card supported:350mm

*Specified power adapter is required.

NVIDIA 3060

*Support advanced graphics card



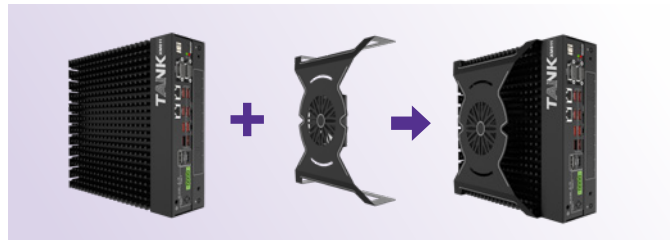
Flexible Expansion

Different expansion requirements can be met. Dual-slot and four-slot SKUs are provided for selection. Customers can choose the type of expansion slot according to their needs.



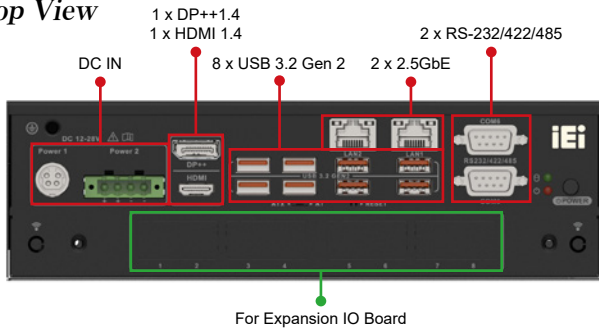
External Fan

Installing an external fan helps to increase system performance in harsh environment.

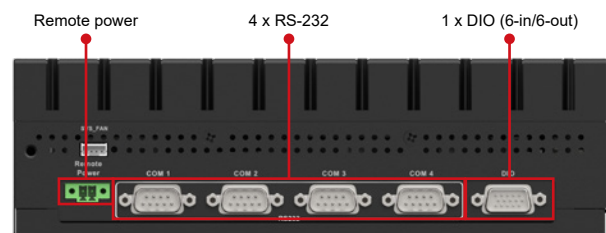


Fully Integrated I/O

Top View

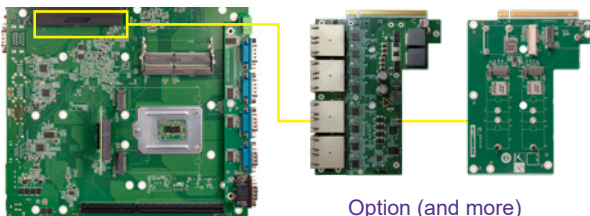


Front View



Modular Board Design

It supports various optional modules, such as M.2 expansion card, 8-port PoE expansion card, etc.



Expansion IO Board	
GPOE-XM81-8P-R10	I/O expansion module for TANK 81 series, 8 x 2.5G LAN with PoE
TXIOB-XM81-A-R10	I/O expansion module for TANK 81 series, 2 x M.2 B Key, 1 x M.2 A Key, 1 x PCIe Mini

Support 35W & 65W CPU

Operating temperature:	
With 35w CPU (or 65W CPU PL1 & PL2, default 35W):	-20°C ~ 60°C
With 65w CPU:	-20°C ~ 50°C